

**Dual N-Channel MOSFET** 

### **General Description**

The WSD2022DN33 is the highest performance trench Dual N-Channel MOSFET with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications .

The WSD2022DN33 meet the RoHS and Green Product requirement 100%  $E_{AS}$  guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% E<sub>AS</sub> Guaranteed
- Green Device Available

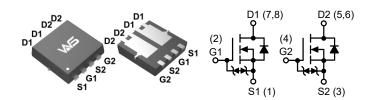
#### **Product Summery**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub>	I <sub>D</sub>	
20V	16.2mΩ	22A	

### **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

#### **DFN3X3-8L Pin Configuration**



### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	V <sub>GS</sub> Gate-Source Voltage		V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	22	
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	4.8	
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	7.4	Α
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	5.7	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	24	
E <sub>AS</sub> Single Pulse Avalanche Energy <sup>3</sup>		15	mJ
I <sub>AS</sub> Avalanche Current		16	Α
P <sub>D</sub> @T <sub>C</sub> =25°C	Power Dissipation <sup>4</sup>	2.5	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Power Dissipation <sup>4</sup>	1.6	VV
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	

#### **Thermal Data**

Symbol Parameter		Тур.	Max.	Units
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient <sup>1</sup>		75	°CAA
R <sub>eJC</sub>	R <sub>e,JC</sub> Thermal Resistance, Junction-to-Case <sup>1</sup>		8.5	°C/W

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## **Electrical Characteristics** (T<sub>J</sub>=25°C, Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250μA	20			V
$\Delta BV_{DSS}/\Delta T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA		0.0332		V/°C
В	Static Brain Source On Besintance 2	V <sub>GS</sub> =4.5V , I <sub>D</sub> =8A		16.2	21	0
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =2.5V , I <sub>D</sub> =7A		19.4	25	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	\/ -\/     -250\	0.4	0.52	1.0	V
$\Delta V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	- V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA		-5.08		mV/°C
	Drain Source Leekage Current	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1.0	
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5.0	μA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>DS</sub> =0V , V <sub>GS</sub> =±8V			±10	μA
9 <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =6.5A		13		S
$R_g$	Gate Resistance	$V_{DS}$ =0V , $V_{GS}$ =0V , f = 1.0MHz		2.2	3.0	Ω
Qg	Total Gate Charge (4.5V)			13.8	17.94	
$Q_gs$	Gate-Source Charge	$V_{DS}$ =10V , $V_{GS}$ =4.5V , $I_{D}$ =8A		4.1	5.33	nC
$Q_gd$	Gate-Drain Charge			5.6	7.28	
T <sub>d(on)</sub>	Turn-On Delay Time			6.2	12.4	
T <sub>r</sub>	Rise Time	$V_{DD}$ =10V , $V_{GEN}$ =5V , $R_{G}$ =3 $\Omega$		12.7	25.4	
$T_{d(off)}$	Turn-Off Delay Time	$I_D=1A$ , $R_L=1.5\Omega$		51.7	103.4	ns
T <sub>f</sub>	Fall Time			16	32	
C <sub>iss</sub>	Input Capacitance			1160		
C <sub>oss</sub>	Output Capacitance V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f = 1.0MHz			104		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			29		

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
E <sub>AS</sub>	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =7.5A	15			mJ

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
I <sub>S</sub>	Continuous Source Current 1,6	V =V =0V Force Current			5	Α
I <sub>SM</sub>	Pulsed Source Curren <sup>2,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			25	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =2A , T <sub>J</sub> =25°C			1.0	V
t <sub>rr</sub>	Reverse Recovery Time	1 -7 5 A 41/4+-100 A /··· T -25°C		13		ns
Q <sub>rr</sub>	Reverse Recovery Charge	l <sub>F</sub> =7.5A, dl/dt=100A/μs,T <sub>J</sub> =25°C		3		nC

#### Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t≤10sec.
- 2. The data tested by pulsed , pulse width  $\leq 300 us$  , duty cycle  $\leq 2\%$
- 3. The E\_{AS} data shows Max. rating . The test condition is  $V_{DD}$ =25V, $V_{GS}$ =10V,L=0.1mH,I\_{AS}=7.5A
- 4. The power dissipation is limited by 150°C junction temperature.
- 5. The Min. value is 100%  $\,{\rm E}_{\rm AS}\,$  tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



## **Typical Characteristics**

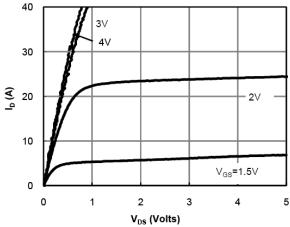
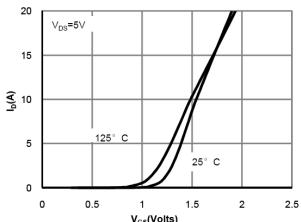
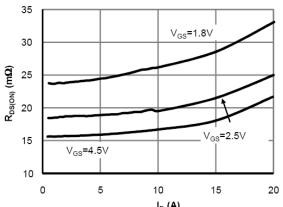


Fig 1: On-Region Characteristics



V<sub>GS</sub>(Volts)
Figure 2: Transfer Characteristics



 $\rm I_{\rm D}$  (A) Figure 3: On-Resistance vs. Drain Current and Gate Voltage

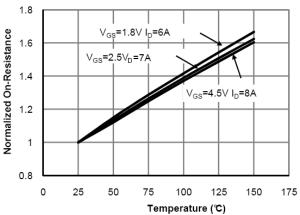
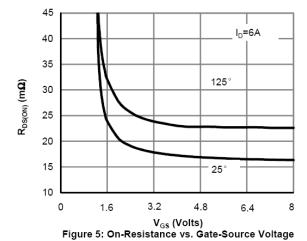
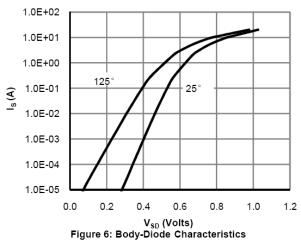


Figure 4: On-Resistance vs. Junction Temperature





10

1

100

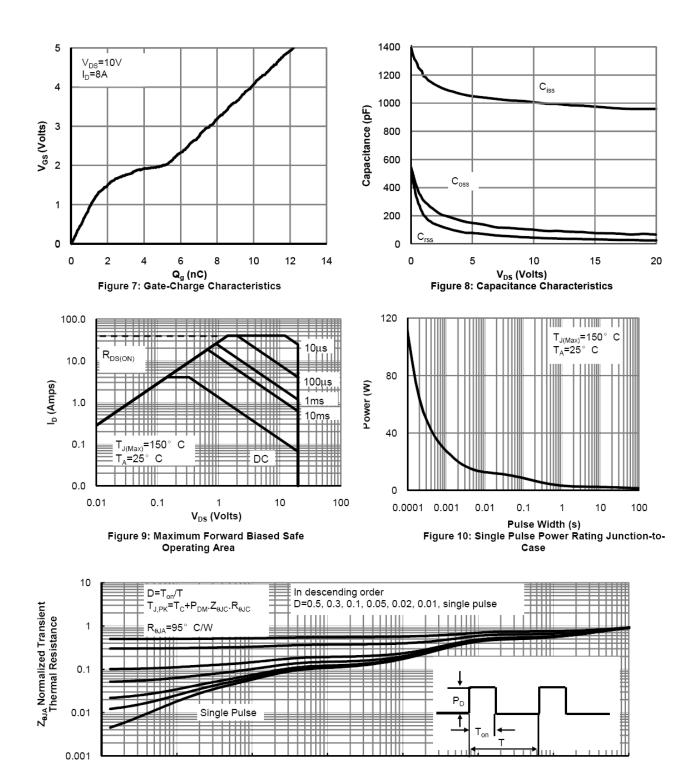


## **Typical Characteristics (Cont.)**

0.00001

0.0001

0.001



Pulse Width (s)
Figure 11: Normalized Maximum Transient Thermal Impedance

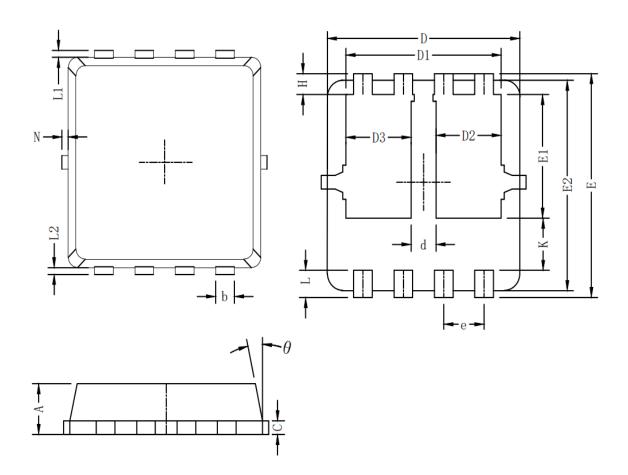
0.01

0.1



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# **Packaging information**



Symbol	Dim in mm				
Symbol	min	typ	max		
А	0.6	0.75	0.9		
b	0.2	0.3	0.4		
С	0.15	0.2	0.25		
D	3	3.1	3.2		
D1	2.3	2.45	2.6		
D2/D3	0.8	1	1.2		
E	3.15	3.3	3.45		
E1	1.43	1.73	1.93		
E2	2.9	3.05	3.2		
е	0.65BSC				
Н	0.2	0.35	0.5		
K	0.57	0.77	0.87		
L	0.3	0.4	0.5		
L1/L2		0.1REF			
θ	8°	10°	13°		
N	0		0.15		
d	0.3	0.4	0.5		



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